



# The 10<sup>th</sup> International Conference on Information and Communication Technology for Embedded Systems

Kasetsart U., Bangkok, Thailand  
March 25-27, 2019

## IMPORTANT DATES

- **30 Dec 2018** Paper Submission Deadline
- **4 Feb 2019** Author Notification
- **22 Feb 2019** Camera Ready and Early Registration Deadline

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## ORGANIZED BY

- **Department of Electrical Engineering,** Kasetsart University (<http://www.ee.ku.ac.th>)
- **Sirindhorn International Institute of Technology,** Thammasat University (<http://www.siit.tu.ac.th>)
- **National Electronics and Computer Technology Center,** NSTDA (<http://www.nectec.or.th>)
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## ABOUT THE CONFERENCE

The 10<sup>th</sup> annual International Conference on Information and Communication Technology for Embedded Systems (IC-ICTES 2019) is to provide an international forum for researchers and industry practitioners. Our goals are to share new ideas, original research results and practical development experiences from all communications, signal processing, and embedded system-related areas including but not limited to embedded system design, development of new HW/SW-related theories and techniques in embedded systems, information and communication system technology. Accepted (by IC-ICTES and IEEE) and presented papers will be published in the IC-ICTES 2019 Conference Proceedings and submitted for inclusion in IEEE Xplore®/IEEE Digital Library.

## AREAS OF INTEREST

### ☞ Communication systems and information technology:

Communication theory, antenna and propagation, microwave theory and techniques, modulation, coding, networks, optical communications, wireless/mobile communications and technologies, smart grid technology, IT bio/medical engineering, business and information systems, information security and forensics, information retrieval and data mining.

### ☞ Signal processing, image processing and sensors:

Digital filters, speech processing and coding, video processing and coding, intelligent signal processing for communications and systems, image processing, hardware/software aspects of sensors, wireless sensor networks.

### ☞ Embedded system architecture:

Multiprocessors, reconfigurable platforms, memory management support, communication, protocols, network-on-chip, real-time systems, embedded Microcontrollers

### ☞ Embedded hardware support and hardware/software co-design:

System-on-a-chip, DSPs, hardware specification, synthesis, modeling, simulation and analysis at all levels for low power, testable, reliable, verifiable systems, performance modeling, validation, security issues, real-time behavior and safety critical systems, methodologies, tests and debug strategies, specification and modeling, design representation, synthesis, partitioning and estimation.

### ☞ Embedded software:

Compilers, assemblers and cross assemblers, programming, memory management, object-oriented aspects, virtual machines, scheduling, concurrent software for SoCs, distributed/resource aware OS, OS and middleware support.

### ☞ Testing techniques:

All aspects of testing, including design-for-test, test synthesis, built-in self-test, embedded test, for embedded and system-on-a-chip systems.

### ☞ Application-specific processors and devices:

Network processors, real-time processor, media and signal processors, application specific hardware accelerators, reconfigurable processors, low power embedded processors, bio/fluidic processors, Bluetooth, hand-held devices.

### ☞ Industrial practices and benchmark suites:

System design, processor design, software, tools, case studies, trends, emerging technologies, experience maintaining benchmark suites, representation, interchange format, tools, copyrights, maintenance, metrics.

### ☞ Emerging new topics:

New challenges for next generation embedded computing systems, arising from new technologies (e.g., nanotechnology), new applications (e.g., IoTs, pervasive or ubiquitous computing, embedded internet tools) and new principle (e.g., embedded engineering).

### ☞ Embedded system applications:

All ranges of applications on embedded system.

## CONFERENCE PUBLICATION AND PAPER SUBMISSION

Proceedings will be published by TAIST Tokyo Tech Program, National Science and Technology Development Agency (NSTDA). The first page should include the paper title, the names and the complete mailing addresses of all authors, and the e-mail address of the corresponding author. Each paper should consist of up to 200-word abstract, up to 5 keywords. No page number should be printed. All the text, figures and reference must be between 4-6 double-column A4 pages with font size of 10 pts. Authors MUST use IEEE manuscript submission guidelines for their initial submissions. All papers must be submitted electronically in PDF format only, using the conference management tool. The submitted papers must not be published or under consideration to be published elsewhere.

## For further information, please contact

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